



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of	)				
	Rajeev Joshi et al.				
Serial No.:	10/618,113				
Filed:	July 11, 2003				
For:	WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME				

## <u>INFORMATION DISCLOSURE STATEMENT</u> <u>UNDER 37 C.F.R.</u> § 1.97

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record believes that the enclosed art is the closest to the claimed invention (taken in its entirety) of which

the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

In accordance with 37 C.F.R. §§ 1.97 and 1.98, a copy of each of the listed references or relevant portion thereof is also enclosed.

Please credit any over payment or charge any additional fees to Deposit Account No. 500843 of the undersigned.

Dated this 30 day of October, 2003.

Respectfully submitted,

Kenneth E. Horton Attorney for Applicant Registration No. 39,481

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KEH:jrj

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	_	DOCUMENT NUMBER		U.S. PAT	ENT DOCUMENTS				
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME		CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
	1	6,187,615	02/13/01	Kim et al.		438	113	12/28/98	
	2	6,287,893	09/11/01	Elenius et al.		438	108	07/13/98	
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EXAMINER 10t consider	R: Initia ed. Inc	l if citation considered, whether o lude copy of this form with next c	r not citation is in ommunication to a	conformanc	e with MPEP Section 609;	Draw line throu	gh citation if not	in conforma	nce and

Form PTO-A820 (also form PTO-1449)

## TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT Docket No. (Under 37 CFR 1.97(b) or 1.97(c)) 11948.21 In Re Application Of: Rajeev Joshi et al. Serial No. Filing Date Examiner Group Art Unit 10/618,113 July 11, 2003 Unassigned Unassigned YEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME Address to: **Assistant Commissioner for Patents** Washington, D.C. 20231 37 CFR 1.97(b) The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114. 37 CFR 1.97(c) 2. $\square$ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of: □ the statement specified in 37 CFR 1.97(e); OR ☐ the fee set forth in 37 CFR 1.17(p).

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT (Under 37 CFR 1.97(b) or 1.97(c))								
Rajeev Joshi et al.								
Serial No. Filing Date		Group Art Unit						
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